Revision Record					
Control No.	**Revision**	**Description**	**Date**	**Drawn**	**Approved**
	A0	Initial release TMAX-1050-2R2-M	2018/08/24	Heter	Roger

TDG HOLDING CO., LTD.

Revision: A0
Control No.:

Recommend Land Pattern Dimensions in millimeters

Marking

z

Inductance and Temperature Rise vs. DC Current

Reliability:

Item	Test Method	Specification and Requirement
Solderability	Solder heat proof : 1.Preheating: 160 r 10°C for 90 seconds 2.Retention time: 245 r 5 for 2 r 0.5 seconds	The surface of termity 9 Tc 0. 0.001 Tc -4.001

Reliability:

Item	Test Method	Specification and Requirement
Thermal Shock	1.Repeat 100 cycle as follow: (-55 r 2	

Packaging Dimensions in millimeters

G	F	I	T	H	A
10.7 r 0.1	12.0 r 0.1	5.5 r 0.1	0.35 r 0.05	16.0 r 0.1	24.0 r 0.3

Reel Dimensions in millimeters

Reflow Profile

Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm^3 Ø350	Volume mm^3 1 350
Ø2.5mm	235	220
12.5mm	220	220

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm^3 Ø350	Volume mm^3 350-

Numbers of taping

z 500 pieces/reel

Label marking

z The following items shall be marked on the production and shipping
z Label on the reel

Production Label

9 Part No.
9 Description
9 Quantity
9 Produce No.
9 Taping No.

Shipping Label

9 Customer's Name
9 Customer's Part No.
9 Manufacturer's Part No.
9 Manufacturer's Name
9 Manufacturer's Country

Care note for use

¾ **Storage Condition**: Temperature 25 to 35°C, Humidity 45 to 75% RH

¾ **Use Temperature**:

9 Minimum Temperature: -55°C Ambient temperature of molded power inductor.

9 Maximum Temperature: +125°C The value of temperature including ambient of the transformer and temperature rise of molded power inductor.

9 There is not a problem from -55°C ~ +125°C in a reliability test.

9 However, this is not meant a temperature grade guarantee of UL.

¾ **Model**: When this molded power inductor was used in a similar or new product to the original one, sometimes it might be unable to satisfy the specifications due to difference of condition of usage.

¾ **Drop**: If the molded power inductor suffered mechanical stress such as drop, characteristics may become poor (due to damage on coil bobbin, etc.).Never use such stressed molded power inductor.

Care note for Safety

¾ Provision to Abnormal Condition

This molded power inductor itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc. Therefore, it shall be confirmed as the end product that there is no risk of smoking, fire, dielectric withstand voltage, insulation resistance, etc. in abnormal conditions to provide protective devices and/or protection circuit in the end product.

¾ Temperature Rise

Temperature rise of molded power inductor depends on the installation condition on end products. It shall be confirmed on the actual end product that temperature rise of molded power inductor is in the limit of specified temperature class.

¾ Dielectric Strength

Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.

¾ Water

This molded power inductor must not be used in wet condition by water, coffee or any liquid because insulation strength becomes very low on the condition.

¾ Potting

If this molded power inductor is potted in some compound, coating material of magnet wire might be occasionally damaged. Please ask us if you intend to pot this molding.

¾ Detergent

Please consult our company once in case of this because the confirmation of reliability etc. is needed when the washing medicine is used for the molded power inductor.

¾ Notes

This electronic component has been designed and developed for usage in general electronic equipment only, not for usage in areas such as military, aerospace, aviation, transportation (automotive control, train control, ship control) etc.. TDG Holding Co., Ltd. must be informed about the intent of such usage before the design-in stage and the parties must have executed an agreement specifically governing such use. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component.